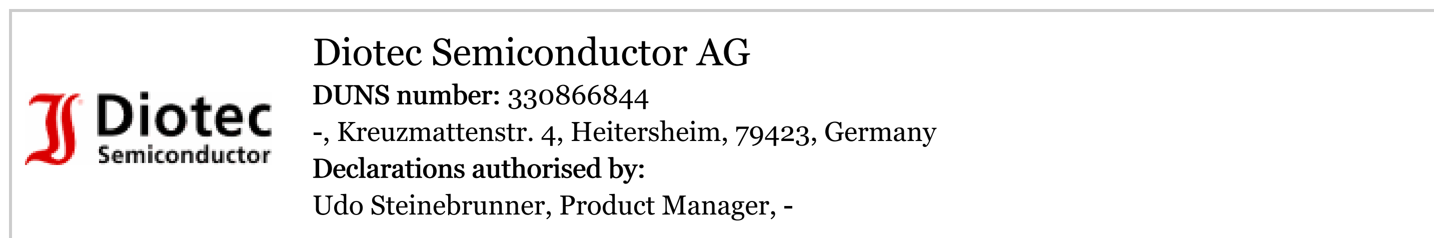
BOMcheck.net

Full Material Declaration for attached parts list

Report generated: 17 December 2025, 14:36 GMT



Diotec Semiconductor AG

DUNS number: 330866844
-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2020 [Approved on 17 December 2025, 14:35 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.71%	ALUMINUM, ELEMENTAL	7429-90-5	0.348%
			Silicon	7440-21-3	99.652%
Die attach	Others (Rubber/non-thermoplastic Elastomer)	0.36%	Diamino-4,4'-diphenyl sulfone	80-08-0	1%
			1,4-BIS(2,3-EPOXYPROPOXY)BUTANE	2425-79-8	7%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	15%
			Silver	7440-22-4	77%
Encapsulation	EP (Epoxy resin)	51.57%	3-(Trimethoxysilyl)propanethiol	4420-74-0	1%
			Carbon black	1333-86-4	1%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	1.5%
			Epoxy resin 89	26335-32-0	10%
			Quartz sand	60676-86-0	86.5%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.17%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.15%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	47.04%	iron	14127-53-8	2.6%
			COPPER, ELEMENTAL	7440-50-8	97.4%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-223 Pb&H-Free (JA)_02	LDO SMD	0.12108	g

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